



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Yoshino, et al.

Docket No.: TI-29448

Serial No.: 09/909,013

Examiner: Geyer, Scott B.

Filed: 07/19/01

Art Unit: 2829

For: Semiconductor Package Insulation Film and Manufacturing Method Thereof

Amendment under 37 CFR 1.111

Assistant Commissioner of Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with the
U.S. Postal Service as First Class Mail in an envelope addressed to:
Assistant Commissioner for Patents, Washington, D.C. 20231 on

9-18-02

Michael K. Skrehot, Reg. No. 36,682

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 06/18/02. They are respectfully submitted as a full and complete response to that Action. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.

10/10/2002: Please amend the specification as follows:

01 FC:102

In the Specification: